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a flexible sheetlike element having terminals thereon associated with each said chip, the terminals of each said sheetlike element being electrically connected to the contacts of the associated chip, the sheetlike element and at least some of the terminals thereon overlying one said surface of the associated chip, the terminals being moveable with respect to the chip to compensate for thermal expansion, the assembly further including resilient means associated with each said chip and sheetlike element for permitting movement of the terminals towards the associated chip said terminals being connected to said contact pads on said substrate..

62. A module as claimed in claim 61 wherein each said chip has a front surface and the contacts of each chip are disposed on the front surface of such chip, the front surface of each chip faces toward the top surface of the substrate and the sheetlike element and terminals associated with each chip overlie the front surface of the chip so that such sheetlike element and terminals are disposed between the front surface and the top surface of the substrate.

63. A module as claimed in claim 62 wherein said sheetlike element includes a thin, flexible, toplayer and wherein said resilient means includes a compliant layer disposed between said top layer and said front surface of each said chip.

64. A module as claimed in claim 62 wherein the front surface of each said chip has a central region and a peripheral region surrounding the central region, whereby said central region is disposed inwardly of said peripheral region, each such chip having a plurality of peripheral contacts disposed in the peripheral region of its front surface, the sheetlike element and terminals associated with each chip overlying the central region of the chip front surface, each terminal being connected to one

of the peripheral contacts on the associated chip by a peripheral contact lead extending inwardly from the contact of the chip to the terminal on the sheetlike element.

¹³65. A module as claimed in claim ⁹61 further comprising one or more discrete components on said substrate electrically connected to said chips by said conductors.

IN THE SPECIFICATION

PAGE 1, LINE 3 BEFORE "TECHNICAL FIELD" INSERT THE FOLLOWING:

-- CROSS-REFERENCE TO RELATED APPLICATION

The present application is a continuation in part of U.S. Patent Application 07/586,758 filed September 24, 1990; now U.S. Patent 5,148,266 a continuation in part of U.S. Patent Application, 07/673,020 filed March 21, 1991, now U.S. Patent 5,148,265; and a continuation of U.S. Patent Application ^{now U.S. Pat. No. 5,347,159} 07/765,928 filed September 24, 1991.--

REMARKS

The present amendment is intended to place the application in better form for examination by correcting typographical errors, by cancelling claims which are redundant in light of similar claims in applicant's copending application 07/765,928 and to incorporate a crossreference to related applications. Further, new claims 61 - 65 have been added to more explicitly point out the aspect of applicant's invention dealing with assemblies of multiple chips to a common substrate with external connections, commonly known in the art as a "module". The attachment of plural chips to a single, common substrate with external connections is disclosed at page 18, lines 15 et seq. The other features incorporated in the newly added claims are referred to, for example, in original claims 1, 2, 5 and 22. The "discrete components" of claim 65 are shown at

reference numeral 32 of the drawings. (Fig. 1) No new matter has been incorporated by addition of these new claims.

INFORMATION DISCLOSURE STATEMENT

Attention is respectfully directed to Fox et al., U.S. Patent 4,954,878, transmitted herewith and listed on the enclosed form PTO-1449.

Respectfully submitted,

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